Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.030”**

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**.030”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: G = .005” X .006” S = .006 x .006”**

**Backside Potential: DRAIN**

**Mask Ref: M46-A**

**APPROVED BY: DK DIE SIZE .030” X .030” DATE: 10/5/22**

**MFG: ZETEX THICKNESS .007” P/N: BSS138**

**DG 10.1.2**

#### Rev B, 7/1